# Plaskon SMT-B-1FX

## Epoxy; Epoxide

## Cookson Electronics - Semiconductor Products

### Message:

This material is an epoxy molding compound optimized specifically for PBGA applications. It is a reduced catalyst version of SMT-B-1F and provides a 1-2% wire sweep improvement in most applications. It has the same unique resin system as the SMT-B-1, which minimizes warpage and enables trouble-free molding onto rigid and flexible laminate substrates. Minimal dimensional change after molding, post bake and subsequent solder treatment make this compound an excellent choice for PBGA applications.

General Information			
Features	Semi-conductive		
	Good dimensional stability		
	Low warpage		
	Low viscosity		
	Fast curing		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.89	g/cm³	ASTM D792
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus			ASTM D790
22°C	1.52	MPa	ASTM D790
215°C	0.461	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.00971	MPa	ASTM D790
215°C	0.00343	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	218	°C	ASTM E1356
CLTE - Flow	1.3E-5	cm/cm/°C	ASTM D696
Thermal Conductivity	0.80	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	Test Method
Volume Resistivity	3.2E+16	ohms·cm	ASTM D257
Dielectric Strength	28	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	3.90		ASTM D150
Dissipation Factor (1 kHz)	4.0E-3		ASTM D150
Flammability	Nominal Value	Unit	Test Method
Flame Rating (3.18 mm)	V-0		UL 94
Oxygen Index	32	%	ASTM D2863
Additional Information			

Recommended Storage Temperature: <5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 monthsLife @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 5 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 2 daysSpiral Flow, 175°C, 1000 psi: 103 cmAutomatic Orifice Viscosity, 175°C: 54 poiseRam Follower Gel Time, 175°C, 1000 psi: 16 secAsh Content: 81 %Hydrolyzable Halides: <1 ppmCull Hot Hardness, Shore D, 75 sec, 175°C: 81Volume Resistivity, 22°C: 3.2e16 ohm-cmAll test specimens are transfer molded and post cured for 4 hours at 175°C Linear Thermal Expansion, Alpha 1: 13 cm^-6/cm/°C

Linear Thermal Expansion, Alpha 2: 53 cm^-6/cm/°C

#### Injection instructions

Resin Transfer Molding: Preheat Temperature: 85 to 98°C Molding Temperature: 175°C Molding Pressure: 800 to 1200 psi Cycle Time, 175°C: 60 to 150 sec Post Mold Cure Time, 175°C: 0 to 4 hr

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#### Recommended distributors for this material

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